

SIM900D-TE_PCB Layout & Schematic for Reference_Application Note_V1.00





Document Title:	SIM900D-TE PCB Layout for Reference				
Version:	1.00				
Date:	2010-8-27				
Status:	Release				
Document Control ID:	SIM900D-TE_PCB Layout & Schematic for				
	Reference_Application Note_V1.00				

General Notes

SIMCOM offers this information as a service to its users, to support application and engineering efforts that use the products designed by SIMCOM. The information provided is based upon requirements specifically provided to SIMCOM by the users. SIMCOM has not undertaken any independent search for additional relevant information, including any information that may be in the user's possession. Furthermore, system validation of this product designed by SIMCOM within a larger electronic system remains the responsibility of the user or the user's system integrator. All specifications supplied herein are subject to change.

Copyright

This document contains proprietary technical information which is the property of SIMCOM Limited., copying of this document and giving it to others and the using or communication of the contents thereof, are forbidden without express authority. Offenders are liable to the payment of damages. All rights reserved in the event of grant of a patent or the registration of a utility model or design. All specification supplied herein are subject to change without notice at any time.

Copyright © Shanghai SIMCOM Wireless Solutions Ltd. 2010





Content

1 Introduction	5
2 Schematic	6
3 PCB Layout	8
3.1 The SIM900D-TE PCB's stack up	8
3.2 The SIM900D-TE's PCB layout	
Top Layer	9
Layer 2	10
Layer 3	
Bottom layer	
Silkscreen Top	
Reference designator Top	
Solder mask Top	15
Paste mask Top	
Silkscreen Bottom	
Reference designator Bottom	
Solder mask Bottom	
Paste mask Bottom	



Version History

Data	Version	Description of change	Author
2010-8-27	V1.00	Origin	liya Wang Guoqiang

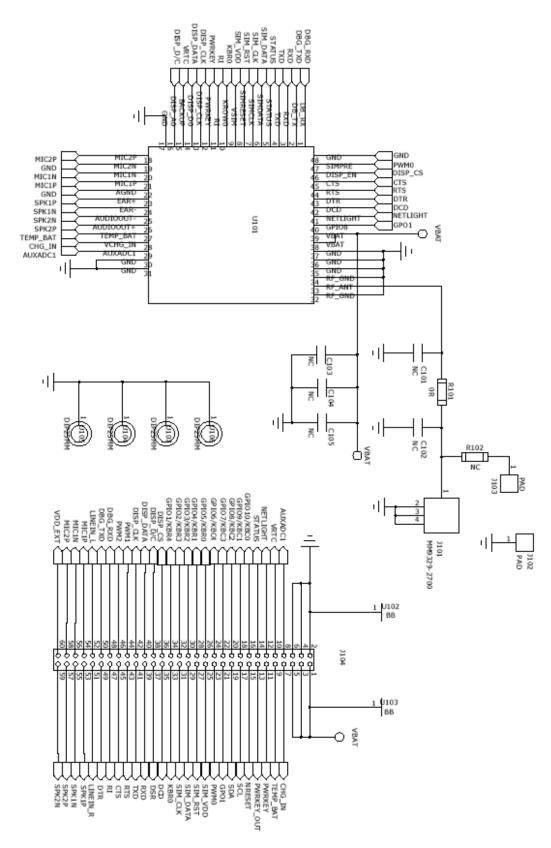


1 Introduction

This document shows the detailed information about SIM900D-TE PCB Layout and Schematic. It is only an illustration for customer. Users should modify the PCB layout based on different cases.



2 Schematic



 $SIM900D\text{-}TE_PCB\ Layout\ \&\ Schematic\ for\ Reference_Application\ Note_V1.00$

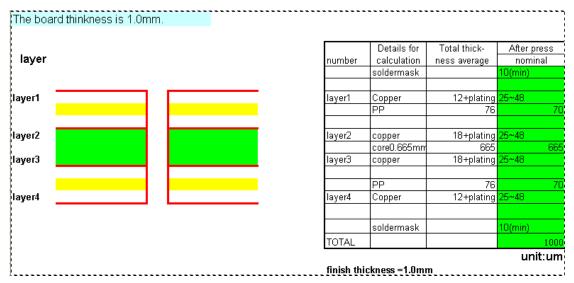


Note: In this schematic, the resistor R102 is an option for choosing either a GSC type coaxial RF cable (MXTK series, vended by Murata) or a soldered coaxial RF cable. The R102 is mounted with a 0ohm resistor, a soldered coaxial RF cable can be chosen for antenna connection, and if the R102 is not mounted, the antenna should be connected via a GSC type coaxial RF cable.



3 PCB Layout

3.1 The SIM900D-TE PCB's stack up



The SIM900D-TE is a four layer PCB, the PCB's total thickness is 1.0mm, the clearance between the first layer and the second layer is 0.076mm, the clearance between the second layer and the third layer is 0.665mm.

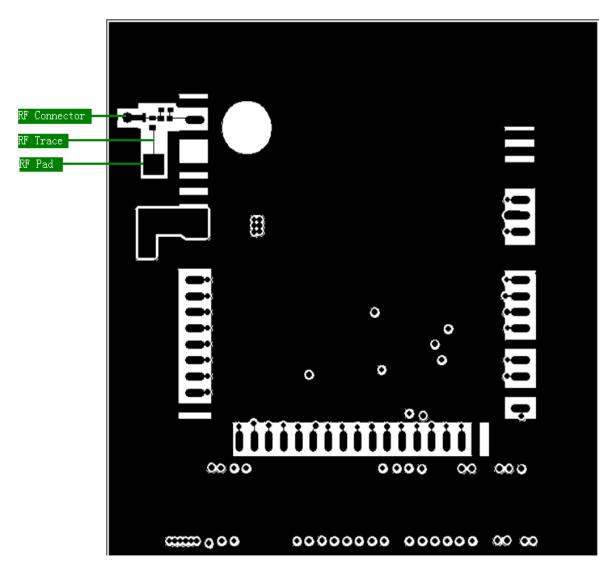
The RF trace is routed on the top layer, and the second layer is the reference ground layer, For the Thickness between the top layer and the second layer is only 0.076mm, so the width of the RF trace on the top layer is 0.11mm.

3.2 The SIM900D-TE's PCB layout

The following pictures are the detailed PCB layout of SIM900D-TE.



Top Layer



1 the RF traces are 50ohm impedance controlled.

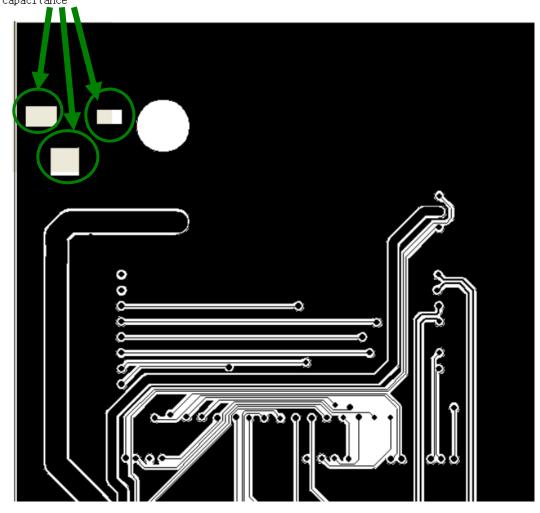
RF connector is matched the GSC coaxial cable assembly, the RF cable should be 50ohm impedance controlled coaxial cable.

RF PAD is used for connect with solderable RF coaxial cable assembly, the RF cable is also should be 50ohm impedance controlled.



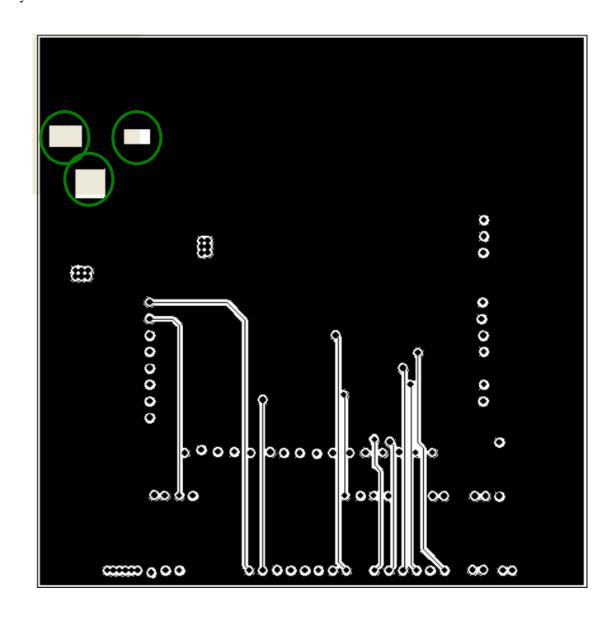
Layer 2

Copper in these area should be keep out to reduce the parasitic capacitance



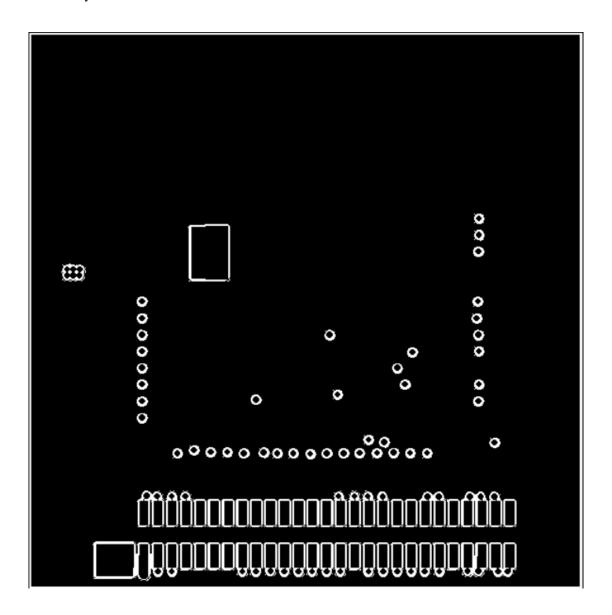


Layer 3



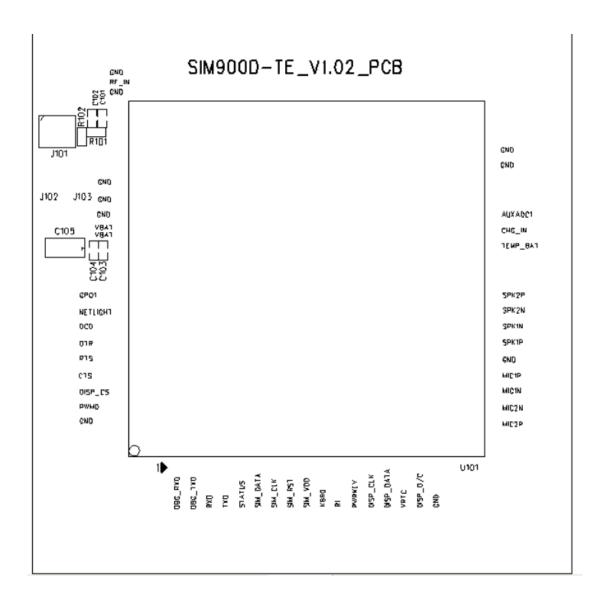


Bottom layer



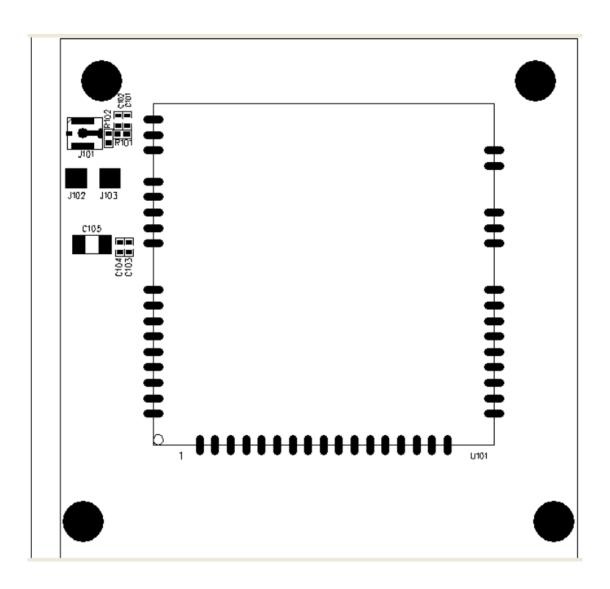


Silkscreen Top



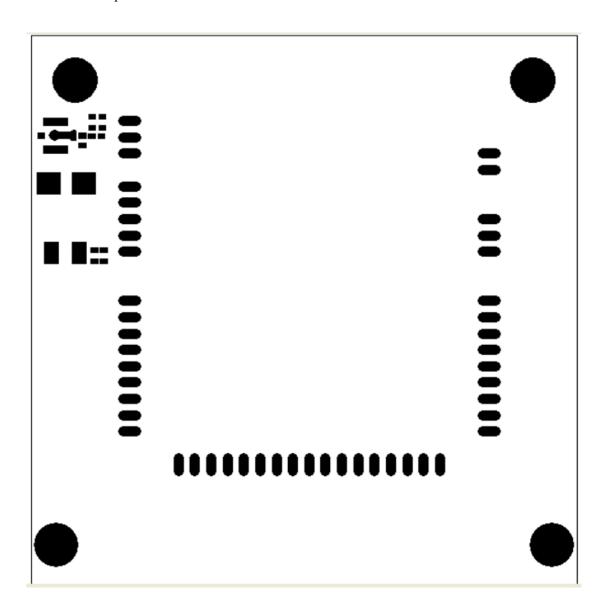


Reference designator Top



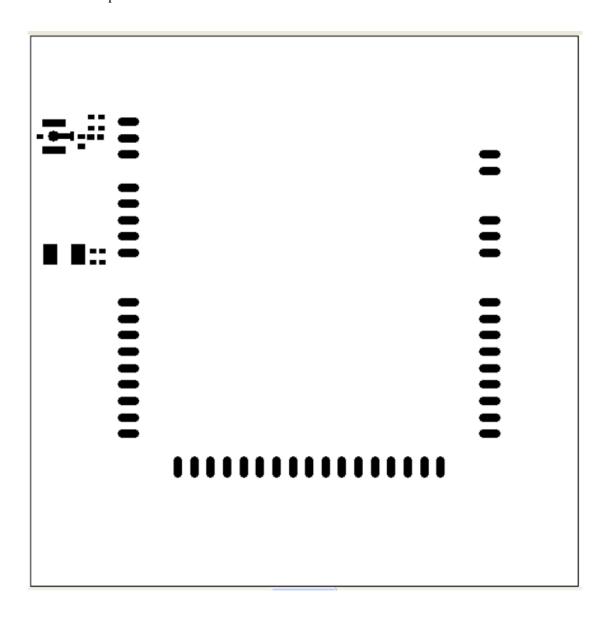


Solder mask Top





Paste mask Top





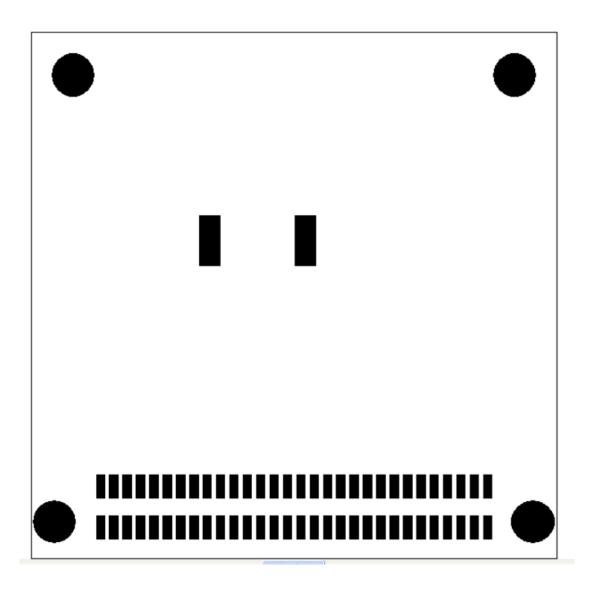
sscreen Bottom				
	J104			
м	HUI1,		09	
			å	
_			10	



eference designator Bottom				
		J104		
65				2
29				_
<u> </u>				



Solder mask Bottom





ste mas	sk Bottom

Contact us:

Shanghai SIMCOM Wireless Solutions Ltd

Add: SIM Technology Building, No. 633, JinZhong Road, Shanghai, PRChina 200335

Tel: +86 21 32523300 Fax: +86 21 32523200 URL:www.sim.com